

Please amend the claims as follows:

In accordance with 37 CFR §1.121, please renumber claims 40 - 43 (1<sup>st</sup> Claim 43) as claims 39-42 as shown below.

**Claims 1-36 (Cancelled)**

37. A process for the production of a wiring board, comprising the steps of:  
defining an opening at a predetermined position of a film-like insulating substrate;

forming a conductive thin film on a principal plane of said insulating substrate;  
etching said conductive thin film to form an electric wiring provided with a connection terminal covering said opening; and

forming a conductive member having a thickness equal to or thinner than that of said insulating substrate.

38. A process for the production of a wiring board, comprising the steps of:  
defining an opening at a predetermined position of a film-like insulating substrate;

forming a conductive thin film on a principal plane of said insulating substrate;  
etching said conductive thin film to form an electric wiring provided with a connection terminal covering said opening;

forming a conductive member having a thickness equal to or thinner than that of said insulating substrate; and

forming sequentially a thin film layer made of nickel (Ni) and a thin film layer made of gold (Au) on the surfaces of said electric wiring and said conductive member.

**[[40.]] 39. (Currently amended)** A process for the production of a wiring board as claimed in claim 37, wherein:

a step for forming said conductive member is effected by forming a copper (Cu) plating or a nickel (Ni) plating in accordance with electroplating method.

**[[41.]] 40. (Currently amended)** A process for the production of a wiring board as claimed in claim 38, wherein:

a step for forming said conductive member is effected by forming a copper (Cu) plating or a nickel (Ni) plating in accordance with electroplating method.

**[[42.]] 41. (Currently amended)** A process for the production of a wiring board as claimed in claim 37, wherein:

a step for forming said conductive member is effected by forming a nickel (Ni) plating in accordance with electroless plating method.

**[[43.]] 42. (Currently amended)** A process for the production of a wiring board as claimed in claim 38, wherein:

a step for forming said conductive member is effected by forming a nickel (Ni) plating in accordance with electroless plating method.

**43. (Original)** A process for the production of a wiring board as claimed in claim 37, wherein:

a step for forming said conductive member is effected by such a manner that the inside of said opening is filled with a conductive paste of silver (Ag) or copper (Cu), and said conductive paste is solidified.

**44. (Original)** A process for the production of a wiring board as claimed in claim 38, wherein:

a step for forming said conductive member is effected by such a manner that the inside of said opening is filled with a conductive paste of silver (Ag) or copper

(Cu), and said conductive paste is solidified.

45. **(Original)** A process for the production of a wiring board as claimed in claim 37, wherein:

a step for forming said conductive member is effected by such a manner that said conductive member has a thinner thickness at the central portion of said opening than that of a vicinity of a side wall of said opening.

46. **(Original)** A process for the production of a wiring board as claimed in claim 38, wherein:

a step for forming said conductive member is effected by such a manner that said conductive member has a thinner thickness at the central portion of said opening than that of a vicinity of a side wall of said opening.

47. **(Original)** A process for the production of a wiring board as claimed in claim 39, wherein:

a step for forming said conductive member is effected by such a manner that said conductive member has a thinner thickness at the central portion of said opening than that of a vicinity of a side wall of said opening.

48. **(Original)** A process for the production of a wiring board as claimed in claim 41, wherein:

a step for forming said conductive member is effected by such a manner that said conductive member has a thinner thickness at the central portion of said opening than that of a vicinity of a side wall of said opening.

49. (Original) A process for the production of a wiring board as claimed in claim 43, wherein:

a step for forming said conductive member is effected by such a manner that said conductive member has a thinner thickness at the central portion of said opening than that of a vicinity of a side wall of said opening.